





PATENT 0171-0759P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

Shoichi OSADA et al.

Conf.:

9440

Appl. No.:

09/883,276

Group:

1712

Filed:

June 19, 2001

Examiner: Marc ZIMMER

For:

SEMICONDUCTOR ENCAPSULATING EPOXY RESIN

COMPOSITION AND SEMICONDUCTOR DEVICE

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 November 3, 2003

Sir:

Transmitted herewith is an amendment in the above-identified application.

| | The enclosed document is being transmitted via the Cert | ificate |
|--|---|---------|
| | of Mailing provisions of 37 C.F.R. § 1.8. | |
| | of Mailing provisions of 5, cut | |

The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

| | CLAIMS REMAINING AFTER AMENDMENT | | HIGHEST NUMBER PREVIOUSLY PAID FOR | | PRESENT EXTRA | RATE | ADDITIONAL FEE |
|-------------|---|---|---|---|------------------|-------|-------------------|
| TOTAL | 13 | - | 20 | = | 0 | \$ 18 | \$0.00 |
| INDEPENDENT | 4 | - | 3 | = | 1 | \$ 86 | \$86.00 |
| | TATION OF A MULTIPLE DEPENDENT CLAIM | | | | | \$290 | \$0.00 |
| | | | | | | TOTAL | \$86.00 |

| | Petition for () mo 37 C.F.R. §§ 1.17 and 1 time. | onth(s) extension of time purs .136(a). \$0.00 for the exten | uant to sion of | | | | |
|--|--|---|--------------------|--|--|--|--|
| | No fee is required. | | | | | | |
| \boxtimes | | f \$86.00 is(are) enclosed. | | | | | |
| | Please charge Deposit A \$0.00. This form is subm | ccount No. 02-2448 in the am itted in triplicate. | ount of | | | | |
| If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees. | | | | | | | |
| | | Respectfully submitted, | | | | | |
| | | BIRCH, STEWART, KOLASCH & BII | RCH, LLP | | | | |
| | | Andrew D. Meikle, #32,868 | | | | | |
| | (/ /RG:gmh 1-0759P | P.O. Box 747 Falls Church, VA 22040-0747 (703) 205-8000 | | | | | |
| Att | achment(s) | | (Rev. 09/30/03) | | | | |



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AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 November 3, 2003

Sir:

In response to the Office Action of August 5, 2003, the following amendments and Remarks are respectfully submitted in connection with the above-identified application.

This Paper includes:

Amendment to the specification;

Amended Claim Set; and

Remarks.

11/05/2003 AADDF01 00000017 09883276

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